

Product Change Notification / JAON-14KDXH970

Date:

24-Mar-2022

Product Category:

Interface- Serial Peripherals

PCN Type:

Manufacturing Change

Notification Subject:

CCB 2780.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire and A194-FH lead frame material for selected automotive MCP23S18T-E/MJVAO catalog part number (CPN) available in 24L QFN (4x4x0.9mm) package at NSEB assembly site.

Affected CPNs:

JAON-14KDXH970_Affected_CPN_03242022.pdf JAON-14KDXH970_Affected_CPN_03242022.csv

Notification Text:

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of palladium coated copper with gold flash (CuPdAu) bond wire and A194-FH lead frame material for selected automotive MCP23S18T-E/MJVAO catalog part number (CPN) available in 24L QFN (4x4x0.9mm) package at NSEB assembly site.

Pre and Post Change Summary:

		Pre Change	Post Change				
Assembly Site		UTAC Thai Limited (UTL-1) LTD (NSEB)	UTAC Thai Limited (UTL-1) LTD (NSEB)				
Wire Material		Au	CuPdAu				
Die Attach Material		8600	8600				
Molding Compound Material		G700LTD	G700LTD				
	Material	EFTEC-64T	A194-FH				
Lead-Frame	DAP Surface	Ag Ring	Ag on lead only				
	Prep	See Pre and post change comparison					

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire and A194-FH lead frame material at NSEB assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: April 30, 2022 (date code: 2218)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	October 2021				>	March 2022					April 2022				
Workweek	4	4	4	4	4		1	1	1	1	1	1	1	1	1
VVOIKVVEEK	1	2	3	4	5		0	1	2	3	4	5	6	7	8
Initial PCN Issue															
Date			Х												
Qual Report															
Availability										Х					
Final PCN Issue															
Date										Х					
Estimated															
Implementation															х
Date															

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:October 19, 2021: Issued initial notification. March 24, 2022: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on April 30, 2022.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_JAON-14KDXH970_Qual Report.pdf PCN_JAON-14KDXH970_Pre and Post Change Summary.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. JAON-14KDXH970 - CCB 2780.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire and A194-FH lead frame material for selected automotive MCP23S18T-E/MJVAO catalog part number (CPN) available in 24L QFN (4x4x0.9mm) package at NSEB assembly site.

Affected Catalog Part Numbers (CPN)

MCP23S18T-E/MJVAO